

SOT546-2

plastic, heatsink ball grid array package; 352 balls; body 35 x 35 x 0.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA352
Package type industry code	HBGA352
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	4-3-2000

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		34.8	-	35	35.2	mm
E	package width		34.8	-	35	35.2	mm
A	seated height		[tbd]	-	1.65	1.65	mm
A ₂	package height		0.8	-	0.9	1	mm
n ₂	actual quantity of termination		-	-	352	-	



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2. Package outline

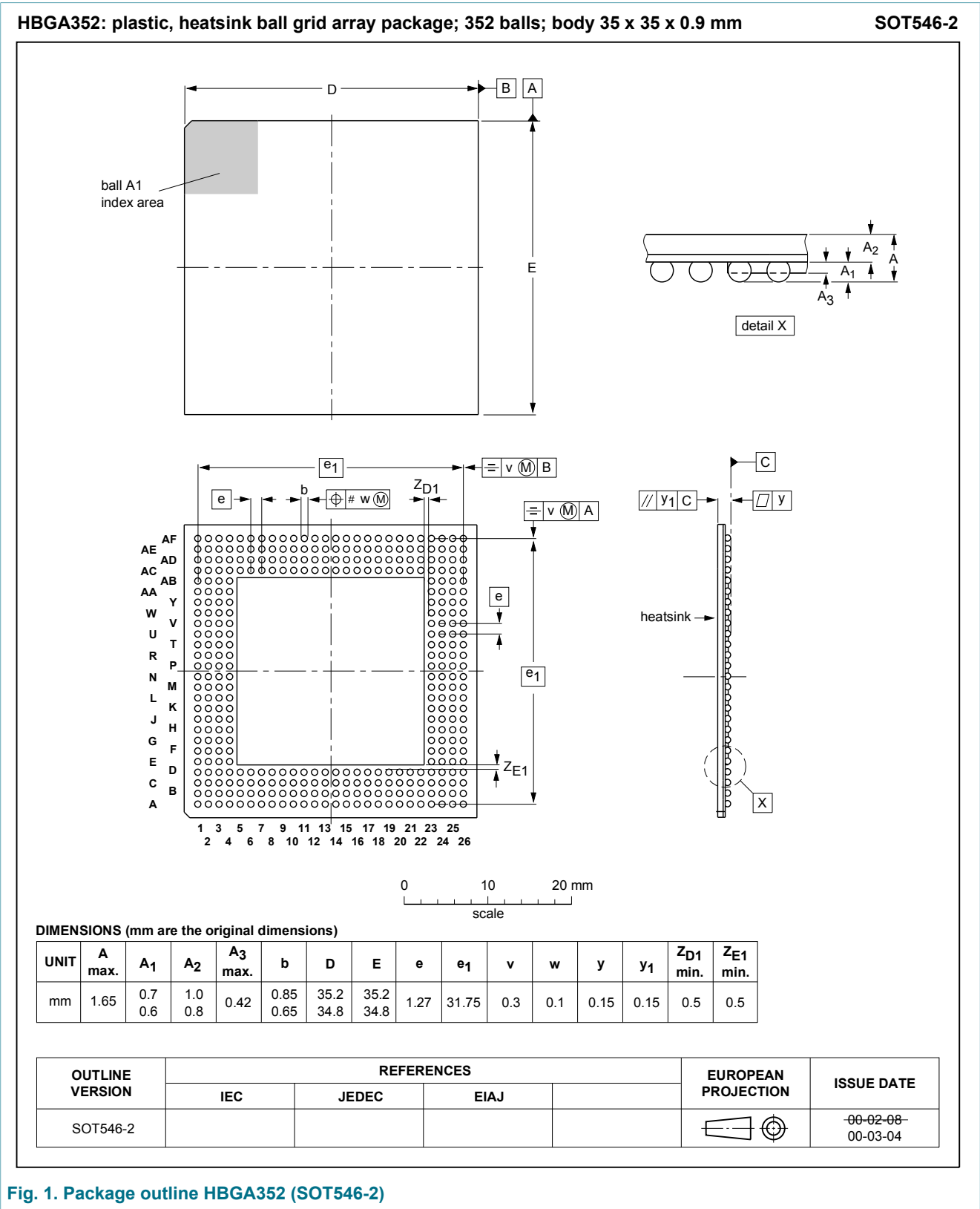


Fig. 1. Package outline HBGA352 (SOT546-2)

3. Soldering

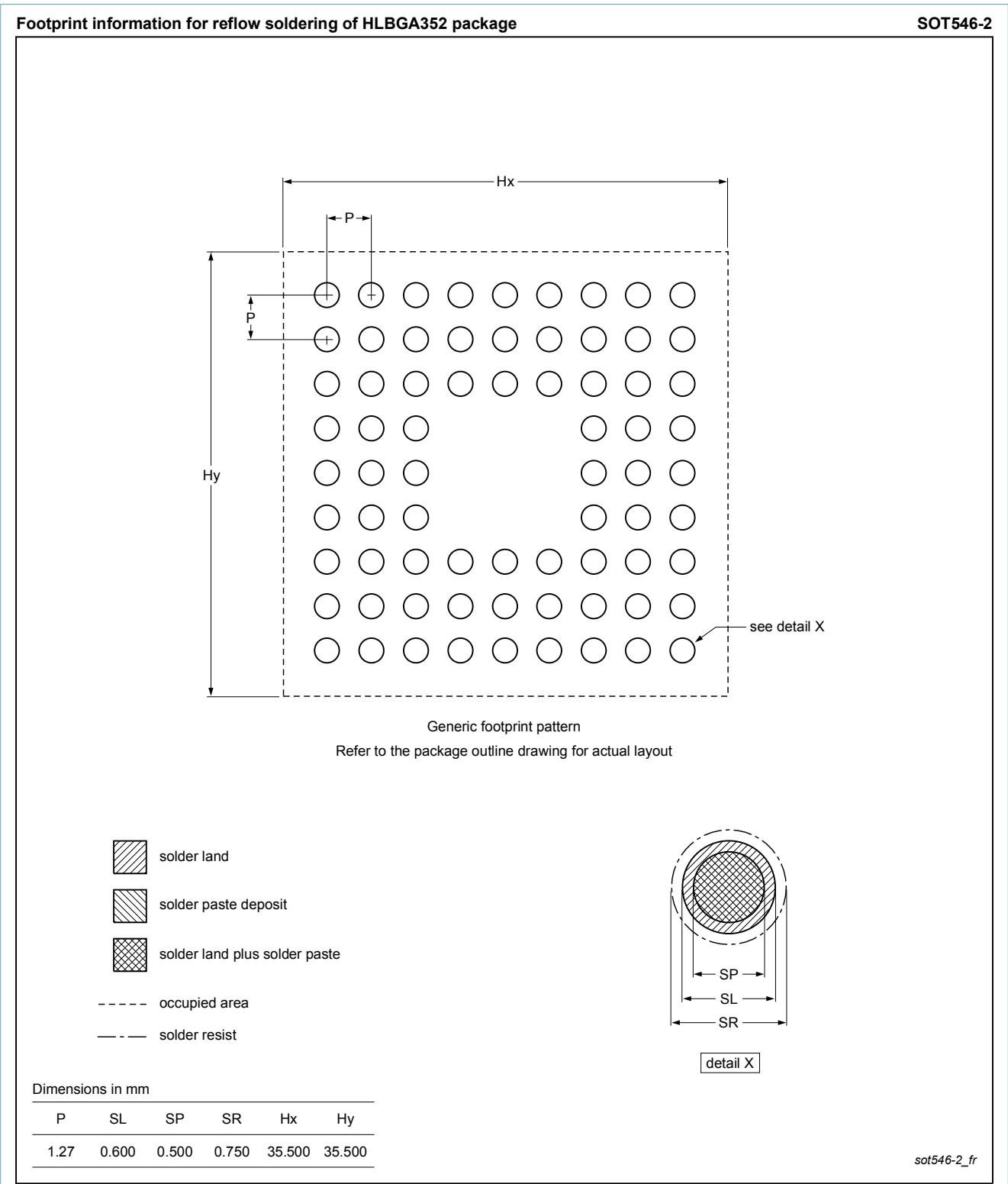


Fig. 2. Reflow soldering footprint for HBGA352 (SOT546-2)

4. Legal information

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